

Alumina ceramic sheet

The unit of the above options is mm.

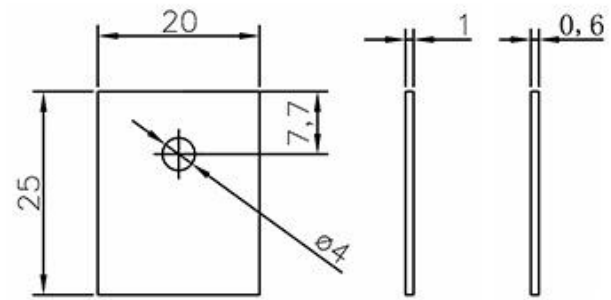
Material: 96% alumina (AL 2O3) white (natural inorganic material)

Thickness: 0.385~0.8~1.0~2.0~3.0~25mm

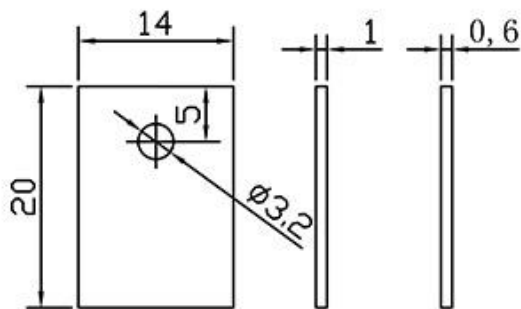
Common specifications: TO-220, TO-247, TO-254, TO-257, TO-258, TO-264, TO-3P, TO-3

氧化铝陶瓷基片性能指标		
性能	Unit	氧化铝陶瓷参数
氧化铝含量	wt%	≥96
体积密度	g/cm ³	≥3.70
硬度 (HRA)	HRA≥	86
抗弯强度	Mpa≥	300
最高使用温度	℃	1600
长期使用温度	℃	1100
气密性测试		Pass
抗热冲击测试		Pass
线膨胀系数	×10 ⁻⁶ /℃	7.5
介电常数	ε _r 20℃, 1MHz	9
介质损耗	tan δ ×10 ⁻¹ , 1MHz	3
体积电阻率	Ω • cm 20℃	10 ¹³
击穿强度	KV/mm. DC≥	20
耐酸性	mg/cm ² ≤	7
耐碱性	mg/cm ² ≤	0.2
耐磨性	g/cm ² ≤	0.2
抗压强度	Mpa≥	2000
抗折强度	Mpa≥	200
弹性模量	G Pa	300
泊松比		0.2
导热系数	W/m • K (20℃)	24

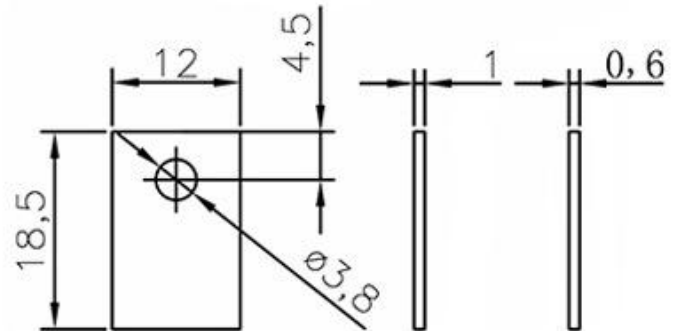
常规型号
图纸展示



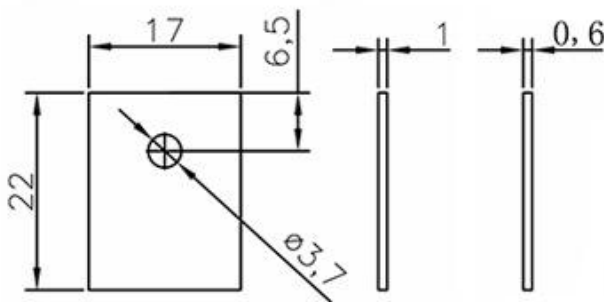
TO-3P



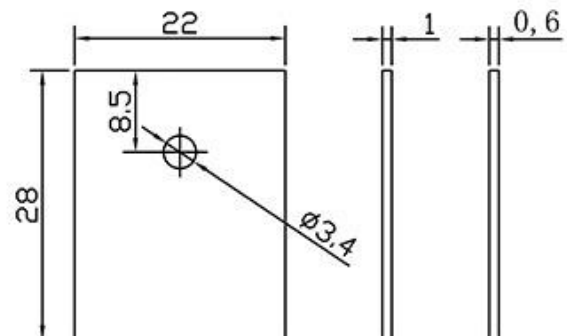
TO-220



TO-220



TO-247



TO-264

Non-standard sizes can be customized, with SGS environmental protection testing.

Alumina ceramic sheet, used for heat dissipation, can replace aluminum heat sink, with high temperature resistance and high thermal conductivity.

Product performance:

1. The ceramic itself does not store heat, directly dissipates heat, and is fast.
2. Ceramics have a polycrystalline structure, which enhances the heat dissipation speed. Year-on-year conditions, surpassing most thermally conductive insulating materials on the market.
3. Ceramic has multi-directional heat dissipation, which further accelerates the heat dissipation speed.
4. Ceramic insulation, high temperature resistance, oxidation resistance, acid and alkali resistance, and long service life.
5. Effective anti-interference (EMI) and anti-static.
6. Natural inorganic materials, in line with environmental protection requirements, in line with EU ROHS environmental protection standards.
7. Small size, light weight, high strength and space saving.
8. Alumina ceramic chip is suitable for IC, MOS, triode, Schottky, IGBT and other surface heat sources that require heat dissipation!
9. It is especially suitable for high-power equipment, and the design space is light, thin, short and small.

use:

Can be used for high-power transistors, field effect tubes, voltage regulator modules (LM78 series, LM317 series, Sanyo power supply thick mode, source thick mode), various audio power amplifier modules (TDA series), high-power thyristor modules (Omron series) , Integrated rectifier module. High-temperature insulation with other electric heating elements; and high-power LED lamp circuit board heat dissipation insulation, high-density switching power supply, high-frequency communication equipment, induction cooker, special heating equipment and other electronic products, equipment, performance is better than mica sheet, silicon film materials !